

CLEAN VERSION OF CLAIMS AFTER AMENDMENT

19. (Amended seven times) A method of assembling a multi-chip device comprising:
providing an interposer having a first surface and a second surface;
populating the second surface with a plurality of conductive pads;
coupling solder balls to selected ones of the plurality of conductive pads;
not coupling the solder balls to non-selected ones of the plurality of conductive pads;
coupling a plurality of cache memory devices and at least one passive device to the first surface to form a multi-chip subassembly, wherein the at least one passive device is selected from a group consisting of resistors, capacitors, and inductors;
testing said plurality of cache memory devices on said interposer;
coupling said interposer to a substrate with the solder balls after said testing if said plurality of cache memory devices pass said testing; and
coupling a microprocessor device to the substrate.

21. (Amended three times) The method of claim 19 wherein the interposer comprises organic material.

22. (temporarily removed from consideration) (Amended once) The method of claim 19 wherein coupling at least one semiconductor die comprises a C4 process.

23. (Amended four times) The method of claim 19 ~~further comprising not coupling said interposer to the substrate if said plurality of cache memory devices does not pass said testing.~~

24. (temporarily removed from consideration) (Amended once) The method of claim 19 further comprising coupling a single chip carrier to the substrate.

25. (temporarily removed from consideration) (Amended once) The method of claim 19 wherein coupling at least one semiconductor die comprises coupling memory chips to the interposer.

26. (Amended once) The method of claim 19, further comprising:
creating a plurality of contacts on the substrate; and
electrically connecting said selected ones of the plurality of conductive pads to the plurality of contacts.